

下列条件适用于 SMD 产品系列内的所有零件：

- 请参照技术手册中的建议设计电路板。
- 必须根据回流焊/波峰焊技术规范选择合格的焊料，严格控制焊接温度、时间。
- 焊接工艺会导致产品表面变色。
- 爬锡现象会导致内孔堵塞，因此通孔产品不适用波峰焊，建议采用回流焊。
- 所有产品应在出厂 12 个月内使用，超出有效期会影响可焊性。
- 必须在密封、干燥环境下保存。
- 零件与 PCB 的连接强度由产品、焊盘、焊接效果等因素综合决定
- 必须控制最大锁附扭力，防止元件和 PCB 受到机械破坏。
- 工作电流由 PCB、电缆接头、电缆横截面等因素综合决定。
- 手册中如有标注参考电流，零件使用材料为黄铜 C3604(H59)

Cautions and Warnings:

The following conditions apply to all goods within the product series of yiyuan PCB SMD

General:

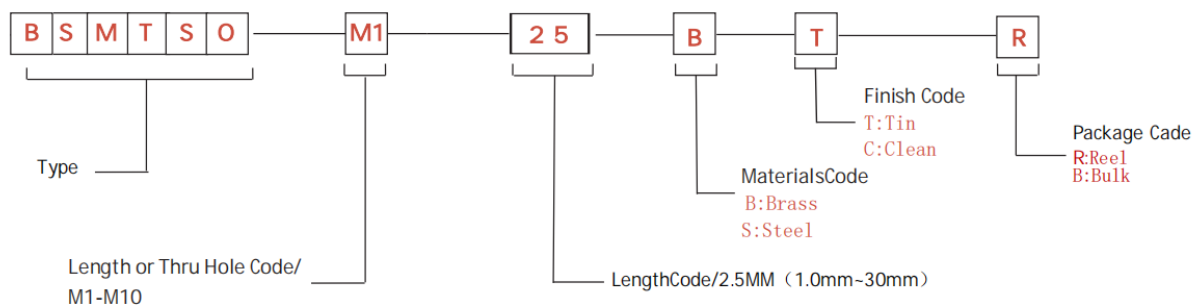
All recommendations according to the general technical specifications of the data-sheet have to be complied with.

The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply for customer specific products.

Product Specific:

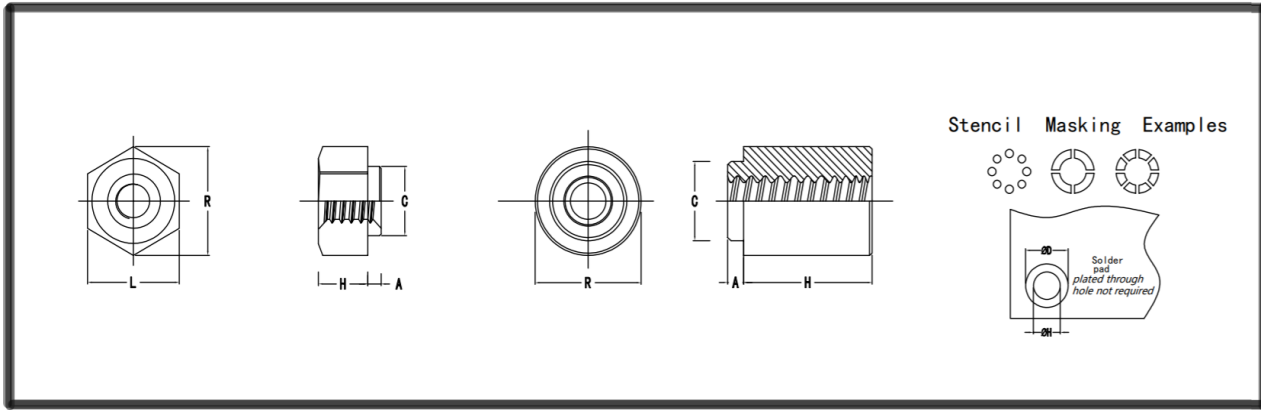
Follow all instructions in the datasheet, especially:

- The solder profile has to be complied with according to the technical reflow soldering specification, otherwise no warranty will be sustained.
- Surface discoloration due to reflow processing is permitted.
- Wave soldering is not applicable. Reflow soldering is recommended.
- All products shall be used before the end of the period of 12 months based on the product date-code, if not a 100% solderability can't be ensured.
- The maximum permissible torques must be complied with to prevent mechanical destruction of the elements and PCB.
- Operating current depends on PCB, cable lug and cross section of the cable.
- The connection strength between parts and PCB is determined by product, pad and welding effect
- If the operating current is marked in the manual, the material used for the parts is brass C3604(H59)



PCB SMD NUT CONNECTOR

电路板表贴螺母柱连接器



Thread sizes 080, S1, S1.2, S1.4 and M1.6

Therad/thru hole sizes M2, M2. 5, M3, M3. 5, M4, 3. 6, 4. 2

All dimensions are in millimeters.

Thread Size x Pitch	Thru Hole +0.10 -0.08	Type	Thread or Thru Hole Code	Length Code "H" ±0.13 (Length code in millimeters)																Below is blind hole with 7mm thread depth Length Code "H" ±0.13 (Length code in millimeters)																Min. Sheet Thickness	A Max.	C Max.	Ref. ±0.13	L Nom.	Hole Size In Sheet +0.08	OD Min.Solder Pad	Rated Current (A)	Tightening Torque (Kgf.cm)
				0.5	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	0.5	0.48	2.41	3.66	3.18	2.5	4.19									
M 1x0.25	—	BSMSTO	M1	0.5	1	1.5	2	2.5	3	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0.5	0.48	2.41	3.66	—	3.18	2.5	4.19	15	0.3								
M1.2x0.25	—	BSMSTO	M1.2	0.5	1	1.5	2	2.5	3	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0.5	0.48	2.41	3.66	—	3.18	2.5	4.19	15	0.6								
M1.4x0.3	—	BSMSTO	M1.4	0.5	1	1.5	2	2.5	3	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0.5	0.48	2.41	3.66	—	3.18	2.5	4.19	15	1								
M1.6x0.35	—	BSMSTO	M1.6	0.5	1	1.5	2	2.5	3	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0.5	0.48	2.41	3.66	—	3.18	2.5	4.19	15	1.5								
M2x0.4	—	BSMSTO	M2	0.5	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	3.6	—	5.56	—	3.73	6.2	30	1.5						
M2.5x0.45	—	BSMSTO	M2.5	—	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	4.09	—	5.56	—	4.22	6.2	30	3						
M3x0.5	—	BSMSTO	M3	—	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	4.09	—	5.56	—	4.22	6.2	30	5						
M3.5x0.6	—	BSMSTO	M3.5	—	—	—	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	5.28	—	7.14	—	5.41	7.77	40	6						
M4x0.7	—	BSMSTO	M4	—	—	—	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	11	12	13	15	18	20	25	30	1.53	1.53	6.22	—	8.74	—	6.35	9.37	50	8						
—	3.2	BSMSTO	K	—	1	1.5	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	—	—	—	—	—	—	—	1.53	1.53	4.09	—	5.56	—	4.22	6.2	20	—							
—	3.6	BSMSTO	L	—	—	—	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	—	—	—	—	—	—	—	1.53	1.53	5.28	—	7.14	—	5.41	7.77	30	—							
—	4.2	BSMSTO	M	—	—	—	2	2.5	3	3.5	4	4.5	5	5.5	6	6.5	7	8	9	10	—	—	—	—	—	—	—	1.53	1.53	6.22	—	8.74	—	6.35	9.37	40	—							

*更多"L"尺寸未列在表中, 请略我们确认! MORE "L" SIZES ARE NOT LISTED IN THE TABLE, PLEASE CONTACT US FOR CONFIRMATIO

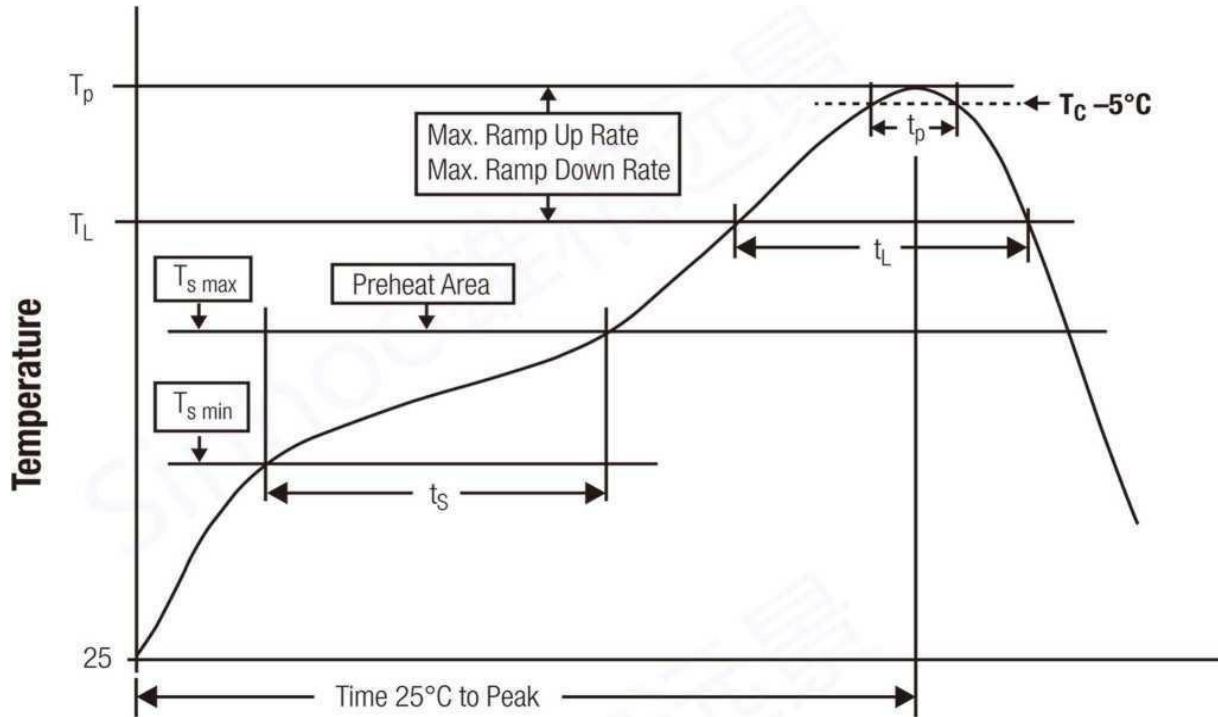
Thread sizes 0, S1, S1.2, S1.4 and M1.6

Therad/thru hole sizes M2, M. 5, M3, M3. 5, M4, 3. 6, 4. 2

2, 4, 6, 8, 116 and 143

All dimensions are in inches.

Thread Size	Thru Hole +.004 -.003	Type	Thread or Thru Hole Code	Length Code "H" ±.005 (Length code in 32nds of an inch)																Min. Sheet Thickness	A Max.	C Max.	R		L Nom.	OH Hole Size In Sheet +.003-.000	OD Min.Solder Pad	Rated Current (A)	Tightening Torque (Kgf.cm)
				Ref.	±.005																								
.060-80 (#0-80)	—	BSMSTO	0	.062	.125	—	—	—	—	.020	.019	.095	.144	—	.125	.098	.165	15	1.5										
.086-56 (#2-56)	—	BSMSTO	2	.062	.125	.187	.250	.312	.375	.060	.060	.142	—	.219	—	.147	.244	30	1.5										
.112-40 (#4-40)	—	BSMSTO	4	.062	.125	.187	.250	.312	.375	.060	.060	.161	—	.219	—	.166	.244	30	5										
.060-80 (#6-32)	—	BSMSTO	6	.062	.125	.187	.250	.312	.375	.060	.060	.208	—	.281	—	.213	.306	40	6										
.164-32 (#8-32)	—	BSMSTO	8	.062	.125	.187	.250	.312	.375	.060	.060	.245	—	.344	—	.250	.369	50	8										
—	.116	BSMSTO	9	.062	.125	.187	.250	.312	.375	.060	.060	.161	—	.219	—	.166	.244	30	—										
—	.143	BSMSTO	10	.062	.125	.187	.250	.312	.375	.060	.060	.208	—	.281	—	.213	.306	40	—										



Classification Reflow Profile for SMT components:

Classification Reflow Soldering Profile:

Profile Feature		Value
Preheat Temperature Min ()	L_{min}	150 °C
Preheat Temperature Max	$T_{s\ max}$	200 °C
Preheat Time t_s from $T_{s\ min}$ to $T_{s\ max}$	t_s	60-120 seconds
Ramp-up Rate (T_L to T_p)		3 °C/ second max.
Liquidous Temperature	T_L	217 °C
Time t_L maintained above T_L	t_L	60-150 seconds
Peak package body temperature		see table
Time within 5°C of actual peak temperature	t_p	20 - 30 seconds
Ramp-down Rate (T_L to T_p)		6 °C/ second max.
Time 25°C to peak temperature		8 minutes max.

Package Classification Reflow Temperature:

Time

Properties	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
PB-Free Assembly I Package Thickness < 1.6 mm	260 °C	260 °C	260 °C
PB-Free Assembly I Package Thickness 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
PB-Free Assembly I Package Thickness > 2.5 mm	250 °C	245 °C	245 °C